Low-Voltage CMOS Hex Inverter

With 5 V-Tolerant Inputs

The MC74LCX04 is a high performance hex inverter operating from a 2.0 to 5.5 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX04 inputs to be safely driven from 5 V devices if V_{CC} is less than 5.0 V.

Current drive capability is 24 mA at the outputs.

Features

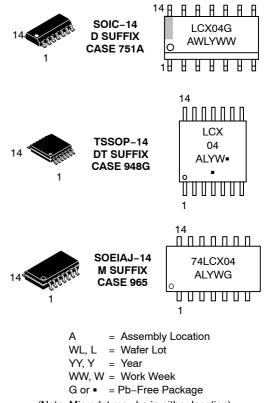
- Designed for 2.0 V to 5.5 V V_{CC} Operation
- 5 V Tolerant Inputs Interface Capability With 5 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 µA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V; Machine Model >200 V
- These Devices are Pb-Free and are RoHS Compliant



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MARKING DIAGRAMS



(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

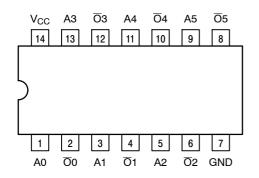


Figure 1. Pinout: 14-Lead (Top View)

PIN NAMES

-

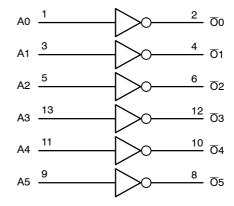


Figure 2. Logic Diagram

TRUTH TABLE

An	Ōn
L	H
H	L

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \leq V_{l} \leq +7.0$		V
Vo	DC Output Voltage	$-0.5 \leq V_O \leq V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
Ι _Ο	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Pa	rameter	Min	Тур	Max	Unit
V_{CC}	Supply Voltage	Operating Data Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	5.5 5.5	V
VI	Input Voltage		0		5.5	V
Vo	Output Voltage	(HIGH or LOW State) (3-State)	0		V _{CC}	V
I _{OH}	HIGH Level Output Current	$V_{CC} = 3.0 V - 3.6 V$ $V_{CC} = 2.7 V - 3.0 V$ $V_{CC} = 2.3 V - 2.7 V$			-24 -12 -8	mA
I _{OL}	LOW Level Output Current	$V_{CC} = 3.0 V - 3.6 V$ $V_{CC} = 2.7 V - 3.0 V$ $V_{CC} = 2.3 V - 2.7 V$			+24 +12 +8	mA
T _A	Operating Free-Air Temperature		-55		+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	, V _{IN} from 0.8 V to 2.0 V, V _{CC} = 3.0 V	0		10	ns/V

DC ELECTRICAL CHARACTERISTICS

			T _A = −55°C		
Symbol	Characteristic	Condition	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage (Note 2)	$2.3 \text{ V} \le \text{V}_{\text{CC}} \le 2.7 \text{ V}$	1.7		V
		$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}$	2.0		
V _{IL}	LOW Level Input Voltage (Note 2)	$2.3 \text{ V} \le \text{V}_{\text{CC}} \le 2.7 \text{ V}$		0.7	V
		$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}$		0.8	
V _{OH}	HIGH Level Output Voltage	2.3 V \leq V_{CC} \leq 3.6 V; I_{OH} = –100 μA	V _{CC} – 0.2		V
		V _{CC} = 2.3 V; I _{OH} = -8 mA	1.8		
		V _{CC} = 2.7 V; I _{OH} = -12 mA	2.2		
		V _{CC} = 3.0 V; I _{OH} = -18 mA	2.4		
		V _{CC} = 3.0 V; I _{OH} = -24 mA	2.2		
V _{OL}	LOW Level Output Voltage	2.3 V \leq V_{CC} \leq 3.6 V; I_{OL} = 100 μA		0.2	V
		V _{CC} = 2.3 V; I _{OL} = 8 mA		0.6	
		V _{CC} = 2.7 V; I _{OL} = 12 mA		0.4	
		$V_{CC} = 3.0 \text{ V}; \text{ I}_{OL} = 16 \text{ mA}$		0.4	
		V _{CC} = 3.0 V; I _{OL} = 24 mA		0.55	
l _l	Input Leakage Current	$2.3~V \leq V_{CC} \leq 3.6~V;~0~V \leq V_l \leq 5.5~V$		±5	μA
I _{CC}	Quiescent Supply Current	2.3 \leq V_{CC} \leq 3.6 V; V_{I} = GND or V_{CC}		10	μΑ
		$2.3 \leq V_{CC} \leq 3.6$ V; $3.6 \leq V_{I}$ or $V_{O} \leq 5.5$ V		±10	
ΔI_{CC}	Increase in I _{CC} per Input	$2.3 \le V_{CC} \le 3.6$ V; $V_{IH} = V_{CC} - 0.6$ V		500	μA

2. These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS t_R = t_F = 2.5 ns; R_L = 500 Ω

			Limits						
			T _A = −55°C to +125°C						
			$V_{CC} = 3.3 V \pm 0.3 V$		V _{CC} =	2.7 V	V _{CC} = 2.5	V \pm 0.2 V	
			C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Мах	Unit
t _{PLH}	Propagation Delay Time	1	1.5	5.2	1.5	6.0	1.5	6.2	ns
t _{PHL}	Input to Output		1.5	5.2	1.5	6.0	1.5	6.2	
t _{OSHL}	Output-to-Output Skew			1.0					ns
t _{OSLH}	(Note 3)			1.0					

 Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

DYNAMIC SWITCHING CHARACTERISTICS

			٦	Γ _A = +25°C	;	
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V _{OLP}	Dynamic LOW Peak Voltage	V_{CC} = 3.3 V, C_L = 50 pF, V_{IH} = 3.3 V, V_{IL} = 0 V		0.8		V
	(Note 4)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = 2.5 V, V_{IL} = 0 V		0.6		V
V _{OLV}	Dynamic LOW Valley Voltage	V_{CC} = 3.3 V, C_L = 50 pF, V_{IH} = 3.3 V, V_{IL} = 0 V		-0.8		V
	(Note 4)	V_{CC} = 2.5 V, C_L = 30 pF, V_{IH} = 2.5 V, V_{IL} = 0 V		-0.6		V

4. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

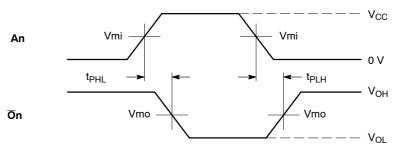
Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	7	pF
C _{OUT}	Output Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	25	pF

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LCX04DG	SOIC-14 (Pb-Free)	55 Units / Rail
MC74LCX04DR2G	SOIC-14 (Pb-Free)	2500 Tape & Reel
MC74LCX04DTG	TSSOP-14* (Pb-Free)	96 Units / Rail
MC74LCX04DTR2G	TSSOP-14* (Pb-Free)	2500 Tape & Reel
MC74LCX04MELG	SOEIAJ-14 (Pb-Free)	2000 Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

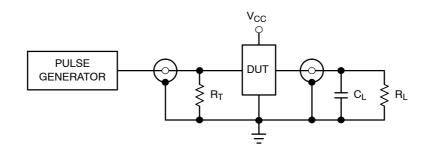
*This package is inherently Pb-Free.



WAVEFORM 1 – PROPAGATION DELAYS t_{R} = t_{F} = 2.5 ns, 10% to 90%; f = 1 MHz; t_{W} = 500 ns

	V _{CC}				
Symbol	$3.3~V~\pm~0.3~V$	2.7 V	$2.5~V~\pm~0.2~V$		
Vmi	1.5 V	1.5 V	V _{CC} /2		
Vmo	1.5 V	1.5 V	V _{CC} /2		



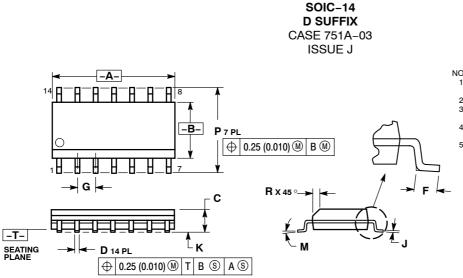


 C_L = 50 pF at V_{CC} = 3.3 ±0.3 V or equivalent (includes jig and probe capacitance) C_L = 30 pF at V_{CC} = 2.5 ±0.2 V or equivalent (includes jig and probe capacitance) R_L = R_1 = 500 Ω or equivalent

 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

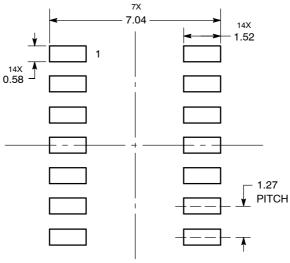
PACKAGE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
Κ	0.10	0.25	0.004	0.009
М	0 °	7 °	0 °	7 °
Ρ	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

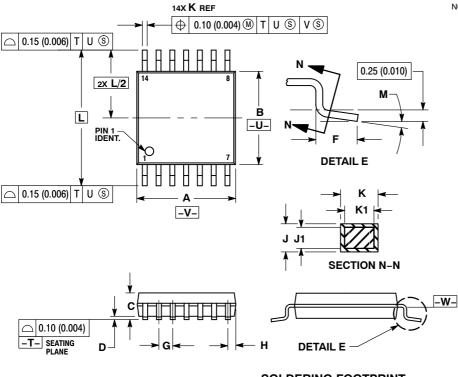
SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

PACKAGE DIMENSIONS

TSSOP-14 **DT SUFFIX** CASE 948G-01 **ISSUE B**



NOTES:

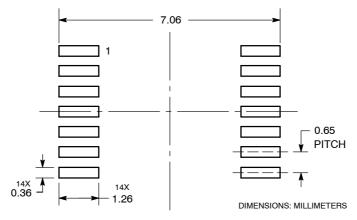
DITES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EVECTOR of the OPEN ONE DE DOING DE DOING

EXCEED 0.15 (0.006) PER SIDE. 4. DIMENSION B DOES NOT INCLUDE

DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
К	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
М	0 °	8 °	0 °	8 °

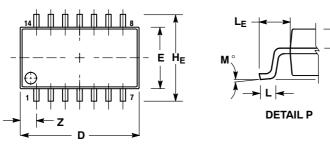
SOLDERING FOOTPRINT

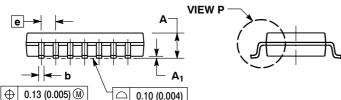


PACKAGE DIMENSIONS

SOEIAJ-14 M SUFFIX CASE 965-01 ISSUE B

Q₁





NOTES:

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.

CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS D AND E DO NOT INCLUDE

MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0 000) PER SIDE

(0.006) PER SIDE. 4. TERMINAL NUMBERS ARE SHOWN FOR BEFERENCE ONLY

REFERENCE ONLY. 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.004	0.008
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
Μ	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Z		1.42		0.056

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